#### 05/13/2014 502806640

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
DAVID M. AUDETTE	05/08/2014
DENNIS M. BRONSON JR.	05/07/2014
JOSEPH K. V. COMEAU	05/07/2014
DUSTIN M. FREGEAU	05/12/2014
DAVID L. GARDELL	05/07/2014
FREDERICK H. ROY III	05/13/2014
JAMES R. SALIMENO III	05/12/2013
TIMOTHY D. SULLIVAN	05/07/2014

### **RECEIVING PARTY DATA**

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### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14276223

### **CORRESPONDENCE DATA**

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PAIENI

**REEL: 032879 FRAME: 0319** 502806640

<b>DATE SIGNED:</b> 05/13/2014		
	This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 6		
source=BUR920140002US1_CombinedAssignment-Declaration#page1.tif		
source=BUR920140002US1_CombinedAssignment-Declaration#page2.tif		
source=BUR920140002US1_CombinedAssignment-Declaration#page3.tif		
source=BUR920140002US1_CombinedAssignment-Declaration#page4.tif		
source=BUR920140002US1_CombinedAssignment-Declaration#page5.tif		
source=BUR920140002US1_CombinedAssignment-Declaration#page6.tif		

PATENT REEL: 032879 FRAME: 0320

# DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT

Title of Invention: SOLDER BUMP ARRAY PROBE TIP STRUCTURE FOR LASER CLEANING

As a below named inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

[x] United States application or PCT international application number 14/276,223 filed on 05/13/2014

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR Section 1.56.

Whereas, the undersigned inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document:

Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor ("ASSIGNOR") hereby sells or has sold, assigns or has assigned, and otherwise transfers or has transferred to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM. its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns,

Page 1 of 3

Each undersigned inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent Application Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Nam	e of Inventor: David M. Audette	
Signature:_	Em Sty Adas	Date: 5/8/2014
(2) Legal Name	e of Inventor: Dennis M. Bronson Jr.	
Signature:_	Penus Browning &	Date:
(3) Legal Name	e of Inventor: Joseph K. V. Comeau	
Signature:	Joseph Comen	Date:5/7/2014
(4) Legal Name	of Inventor: Dustin M. Fregeau	
Signature:	Dott	Date: 5/12/14

[ADDITIONAL SIGNATURE PAGE(S) FOLLOWS]

Page 2 of 3

(5) Legal Name of Inventor; David L. Gardell	
Signature: Signature: Say by M	Date: 5/67/14
(6) Legal Name of Inventor: Frederick H. Roy III	
Signature: Justin 12. Kg/	Date: 5/13/14
(7) Legal Name of Inventor: Jim Salimeno III	
Signature:	Date:
(8) Legal Name of Inventor: Timothy D. Sullivan	
Ciamatana	₩

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Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned inventor ("ASSIGNOR") hereby sells or has sold, assigns or has assigned, and otherwise transfers or has transferred to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Page 1 of 3

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(1)	Legal Name of Inventor: David M. Audette	
	Signature:	Date:
(2)	Legal Name of Inventor: Dennis M. Bronson Jr.	
	Signature:	Date:
(3)	Legal Name of Inventor: Joseph K. V. Comeau	
	Signature:	Date:
(4)	Legal Name of Inventor: Dustin M. Fregeau	
	Signature:	Date:

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Signature:	Date:
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Signature:	Date:
(7) Legal Name of Inventor: Jim Salimeno III  Signature:  Signature:	Date: 5/12/2014
(8) Legal Name of Inventor; Timothy D. Sullivan	
Signature: Tunnahy D. Sullivan	Date: 7 May 2014